

Fujitsu renews packaging license with Tessera on original terms

(September 22, 2010 - BUSINESS WIRE) -- Tessera Technologies, Inc. (Nasdaq:TSRA) announced that Fujitsu Limited, provider of ICT-based business solutions, renewed its worldwide licensing agreement with Tessera's semiconductor packaging subsidiary, [Tessera Inc.](#) Under the agreement, which was renewed in accordance with its original terms, Fujitsu is licensed to Tessera's semiconductor packaging technology covering a broad range of [chip scale](#) and [multi-chip package](#) types.

"We are pleased Fujitsu has renewed its license agreement with us, extending the long-term commercial relationship between our two companies," said Henry R. Nothhaft, chairman and CEO, Tessera. "Tessera provides royalty-bearing licenses to a broad portfolio of semiconductor packaging intellectual property, which is used by leading members of the [semiconductor industry](#) worldwide. We continue our efforts to make our innovative technologies widely available, helping to enable the long-term growth of our served semiconductor markets."

Tessera Technologies, Inc. invests in, licenses and delivers innovative miniaturization technologies for next-generation electronic devices. The company's micro-electronics solutions enable smaller, higher-functionality devices through chip-scale, 3D and wafer-level packaging technology, as well as high-density substrate and silent air cooling technology. For information, go to www.tessera.com.

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